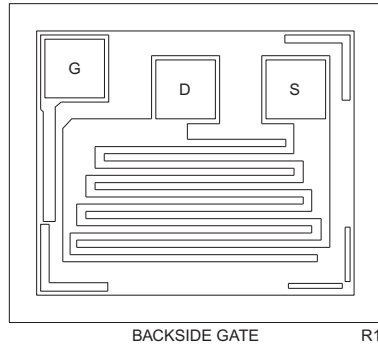


CP206-2N4393

N-Channel JFET Die

The CP206-2N4393 is a silicon N-Channel small signal JFET designed for analog switching and chopper applications.



MECHANICAL SPECIFICATIONS:

Die Size	21 x 18 MILS
Die Thickness	8.0 MILS
Drain Bonding Pad Size	3.0 x 3.0 MILS
Source Bonding Pad Size	3.0 x 3.0 MILS
Gate Bonding Pad Size	3.0 x 3.0 MILS
Top Side Metalization	Al – 30,000Å
Back Side Metalization	Au – 6,000Å
Scribe Alley Width	3.0 MILS
Wafer Diameter	5 INCHES
Gross Die Per Wafer	45,000

MAXIMUM RATINGS: ($T_A=25^{\circ}\text{C}$)

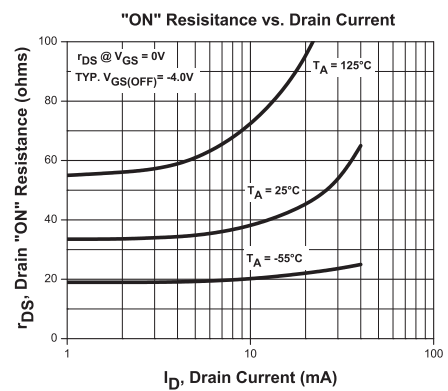
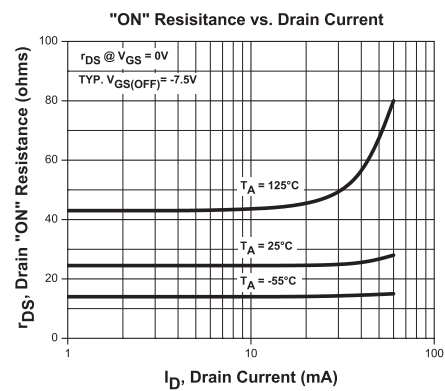
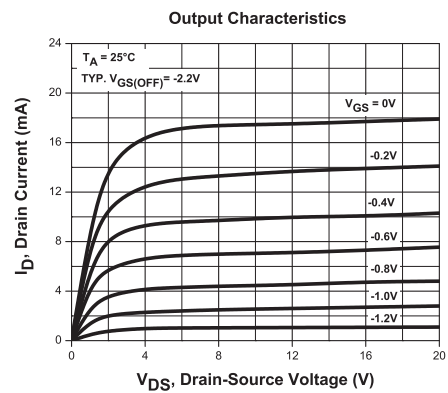
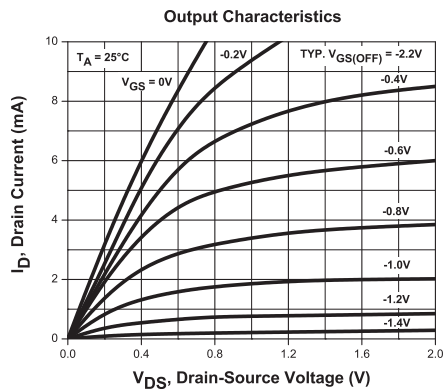
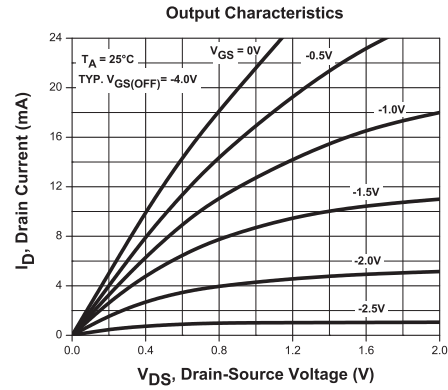
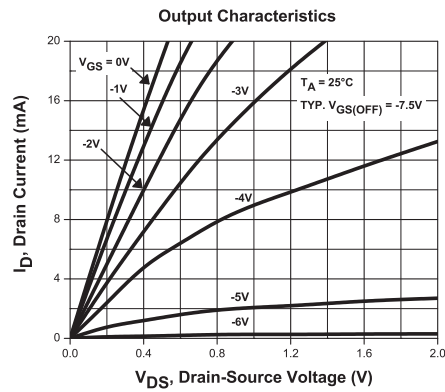
	SYMBOL		UNITS
Gate-Drain Voltage	V_{GD}	40	V
Gate-Source Voltage	V_{GS}	40	V
Gate Current	I_G	50	mA
Operating and Storage Junction Temperature	T_J, T_{stg}	-65 to +175	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS: ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_{GSS}	$V_{GS}=20\text{V}$		0.1	nA
I_{DSS}	$V_{DS}=20\text{V}$	5.0	30	mA
$I_{D(OFF)}$	$V_{DS}=20\text{V}, V_{GS}=5.0\text{V}$		0.1	nA
BV_{GSS}	$I_G=1.0\mu\text{A}$	40		V
$V_{GS(OFF)}$	$V_{DS}=20\text{V}, I_D=1.0\text{nA}$	0.5	3.0	V
$V_{GS(f)}$	$V_{DS}=0, I_G=1.0\text{mA}$		1.0	V
$V_{DS(ON)}$	$I_D=3.0\text{mA}$		0.4	V
$r_{DS(ON)}$	$I_D=1.0\text{mA}, V_{GS}=0$		100	Ω
C_{rss}	$V_{GS}=5.0\text{V}, V_{DS}=0, f=1.0\text{MHz}$		3.5	pF
C_{iss}	$V_{DS}=20\text{V}, V_{GS}=0, f=1.0\text{MHz}$		14	pF
t_{on}	$I_{D(ON)}=3.0\text{mA}$		15	ns
t_{off}	$V_{GS(OFF)}=5.0\text{V}$		50	ns

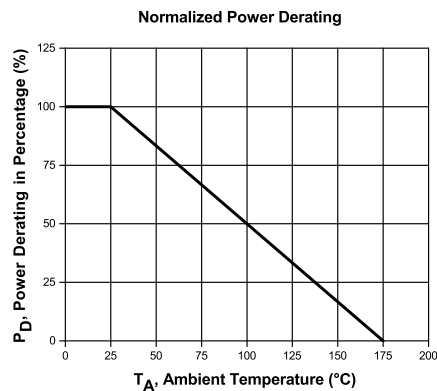
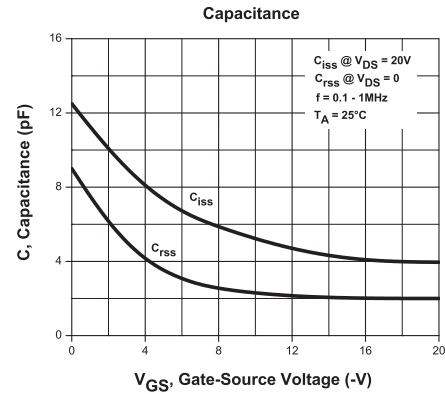
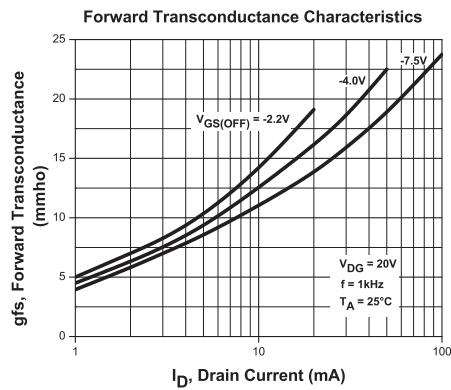
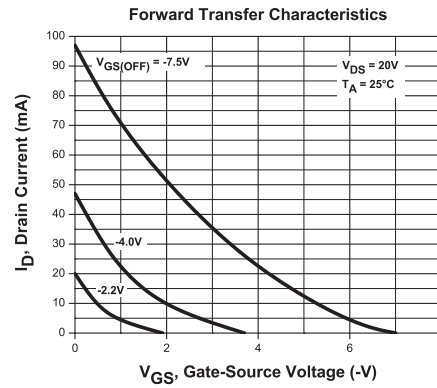
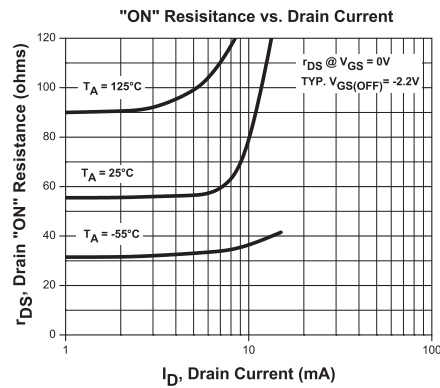
CP206-2N4393

Typical Electrical Characteristics



CP206-2N4393

Typical Electrical Characteristics



R1 (5-February 2016)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centalsemi.com

Worldwide Field Representatives:
www.centalsemi.com/wwreps

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